NTMD4884NF

Power MOSFET and Schottky Diode

30 V, 5.7 A, Single N−Channel with 30 V, 2.8 A, Schottky Barrier Diode

ON Semiconductor®

http://onsemi.com

Features

- FETKY™ Surface Mount Package Saves Board Space
- Independent Pin−Out for MOSFET and Schottky Allowing for Design Flexibility
- Low $R_{DS(on)}$ MOSFET and Low V_F Schottky to Minimize Conduction Losses
- Optimized Gate Charge to Minimize Switching Losses
- This is a Pb−Free Device

Applications

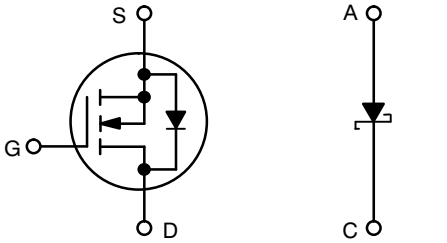
- Disk Drives
- DC−DC Converters
- Printers

N−CHANNEL MOSFET

$V_{(BR)DSS}$	$R_{DS(on)}$ Max	I_D Max
30 V	48 mΩ @ 10 V	5.7 A
	70 mΩ @ 4.5 V	

SCHOTTKY DIODE

V_R Max	V_F Max	I_F Max
30 V	0.5 V	2.8 A



N−Channel MOSFET **Schottky Diode**

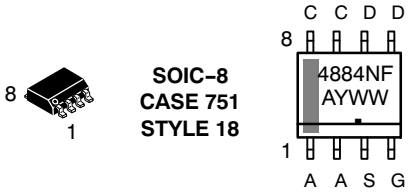
MOSFET MAXIMUM RATINGS (T_J = 25°C unless otherwise stated)

Rating			Symbol	Value	Unit
Drain−to−Source Voltage			V_{DSS}	30	V
Gate−to−Source Voltage			V_{GS}	±20	V
Continuous Drain Current $R_{\theta JA}$ (Note 1)	Steady State	T_A = 25°C	I_D	4.7	A
		T_A = 70°C		3.8	
Power Dissipation $R_{\theta JA}$ (Note 1)		T_A = 25°C	P_D	1.6	W
Continuous Drain Current $R_{\theta JA}$ (Note 2)		T_A = 25°C	I_D	3.3	A
		T_A = 70°C		2.6	
Power Dissipation $R_{\theta JA}$ (Note 2)		T_A = 25°C	P_D	0.77	W
Continuous Drain Current $R_{\theta JA}$ t < 10 s (Note 1)		T_A = 25°C	I_D	5.7	A
		T_A = 70°C		4.5	
Power Dissipation $R_{\theta JA}$ t < 10 s (Note 1)		T_A = 25°C	P_D	2.3	W
Pulsed Drain Current	T_A = 25°C, t_p = 10 μs		I_{DM}	19	A
Operating Junction and Storage Temperature			T_J, T_{STG}	−55 to +150	°C
Source Current (Body Diode)			I_S	1.3	A
Lead Temperature for Soldering Purposes (1/8″ from case for 10 s)			T_L	260	°C

SCHOTTKY MAXIMUM RATINGS (T_J = 25°C unless otherwise stated)

Peak Repetitive Reverse Voltage		V_{RRM}	30	V
DC Blocking Voltage		V_R	30	V
Average Rectified Forward Current, (Note 1)	Steady State	I_F	2.8	A
	t < 10 s		4.1	

MARKING DIAGRAM & PIN ASSIGNMENT



SOIC−8
CASE 751
STYLE 18

4884NF = Device Code
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb−Free Package

ORDERING INFORMATION

Device	Package	Shipping†
NTMD4884NFR2G	SOIC−8 (Pb−Free)	2500/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter MOSFET & Schottky	Symbol	Max	Unit
Junction−to−Ambient − Steady State (Note 1)	$R_{\theta JA}$	79	°C/W
Junction−to−Ambient − t ≤10 s Steady State (Note 1)	$R_{\theta JA}$	54	
Junction−to−FOOT (Drain) Equivalent to $R_{\theta JC}$	$R_{\theta JF}$	50	
Junction−to−Ambient − Steady State (Note 2)	$R_{\theta JA}$	163	

1. Surface−mounted on FR4 board using 1 inch sq pad size, 1 oz Cu.
2. Surface−mounted on FR4 board using the minimum recommended pad size.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Characteristic	Symbol	Test Condition		Min	Typ	Max	Unit
OFF CHARACTERISTICS							
Drain−to−Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0 V, I_D = 250 μA		30			V
Drain−to−Source Breakdown Voltage Temperature Coefficient	$V_{(BR)DSS}/T_J$				24		mV/°C
Zero Gate Voltage Drain Current	I_{DSS}	V_{GS} = 0 V, V_{DS} = 24 V	T_J = 25°C			1.0	μA
			T_J = 125°C			20	
Gate−to−Source Leakage Current	I_{GSS}	V_{DS} = 0 V, V_{GS} = ±20 V				±100	nA
ON CHARACTERISTICS (Note 3)							
Gate Threshold Voltage	$V_{GS(TH)}$	V_{GS} = V_{DS}, I_D = 250 μA		1.0		2.5	V
Negative Threshold Temperature Coefficient	$V_{GS(TH)}/T_J$				5.0		mV/°C
Drain−to−Source On Resistance	$R_{DS(on)}$	V_{GS} = 10 V	I_D = 4.0 A		34	48	mΩ
		V_{GS} = 4.5 V	I_D = 3.5 A		50	70	
Forward Transconductance	g_{FS}	V_{DS} = 5.0 V, I_D = 4.0 A			10		S
Gate Resistance	R_G				2.4	3.6	Ω
CHARGES, CAPACITANCES AND GATE RESISTANCE							
Input Capacitance	C_{ISS}	V_{GS} = 0 V, f = 1.0 MHz, V_{DS} = 15 V			280	360	pF
Output Capacitance	C_{OSS}				60	80	
Reverse Transfer Capacitance	C_{RSS}				32	42	
Total Gate Charge	$Q_{G(TOT)}$	V_{GS} = 4.5 V, V_{DS} = 15 V, I_D = 4.0 A			2.8	4.2	nC
Threshold Gate Charge	$Q_{G(TH)}$				0.4		
Gate−to−Source Charge	Q_{GS}				1.2		
Gate−to−Drain Charge	Q_{GD}				1.0		
Total Gate Charge	$Q_{G(TOT)}$	V_{GS} = 10 V, V_{DS} = 15 V, I_D = 4.0 A			5.6	8.0	nC
SWITCHING CHARACTERISTICS (Note 4)							
Turn−On Delay Time	$t_{d(ON)}$	V_{GS} = 10 V, V_{DS} = 15 V, I_D = 1.0 A, R_G = 6.0 Ω			6.0	12	ns
Rise Time	t_r				6.5	13	
Turn−Off Delay Time	$t_{d(OFF)}$				14	26	
Fall Time	t_f				1.4	7.0	
DRAIN−TO−SOURCE CHARACTERISTICS							
Forward Diode Voltage	V_{SD}	V_{GS} = 0 V, I_D = 1.3 A	T_J = 25°C		0.8	1.0	V
			T_J = 125°C		0.65		
Reverse Recovery Time	t_{RR}	V_{GS} = 0 V, d_{IS}/d_t = 100 A/μs, I_S = 4.0 A			9.2	20	ns
Charge Time	t_a				6.0		
Discharge Time	t_b				3.2		
Reverse Recovery Time	Q_{RR}				3.3		nC

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Characteristic	Symbol	Test Condition	Min	Typ	Max	Unit

SCHOTTKY DIODE ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Parameter	Symbol	Test Conditions		Min	Typ	Max	Unit
Maximum Instantaneous Forward Voltage	V_F	I_F = 0.1 A	T_J = 25°C		0.26	0.28	V
			T_J = 125°C		0.11	0.13	
		I_F = 2.0 A	T_J = 25°C		0.4	0.50	
			T_J = 125°C		0.35	0.46	
Maximum Instantaneous Reverse Current	I_R	V_R = 10 V	T_J = 25°C		0.020	0.25	mA
			T_J = 125°C		10	37	

3. Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.
4. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

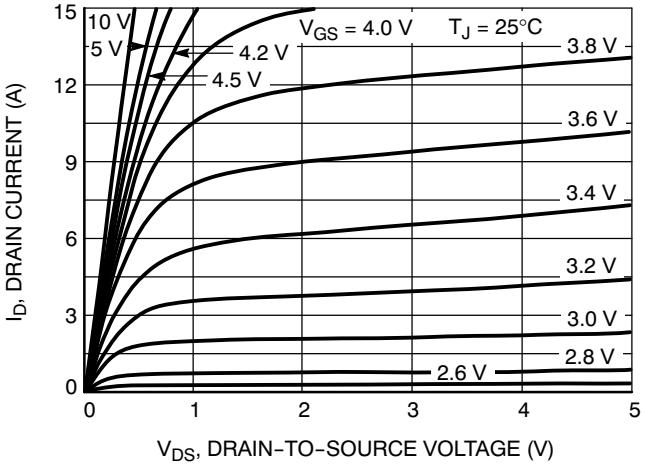


Figure 1. On−Region Characteristics

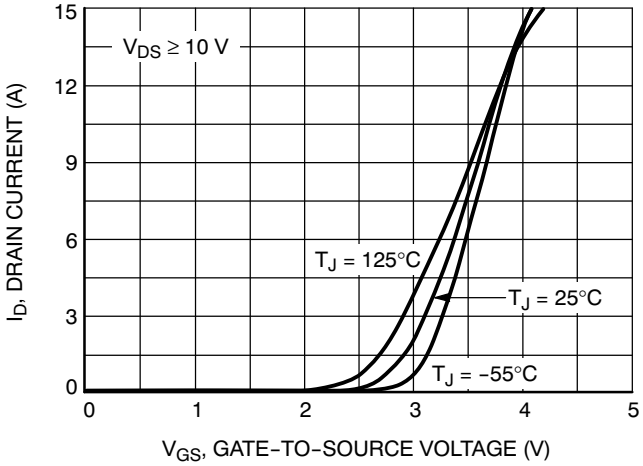


Figure 2. Transfer Characteristics

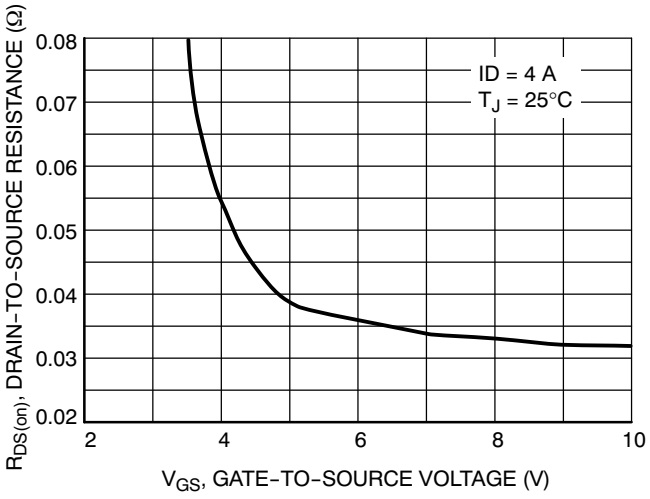


Figure 3. On−Resistance vs. Gate Voltage

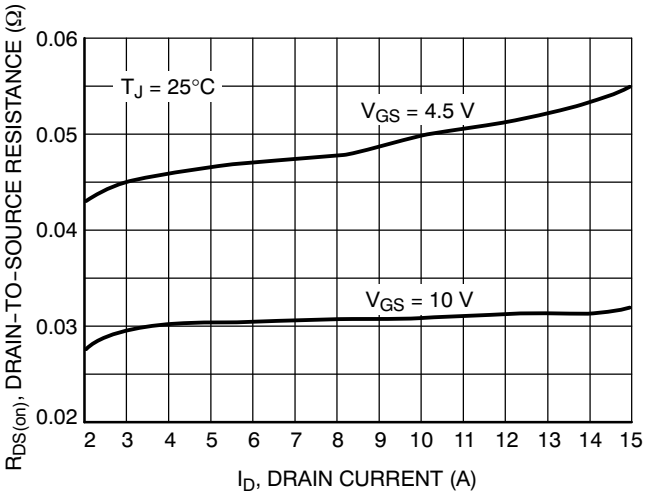


Figure 4. On−Resistance vs. Drain Current and Gate Voltage

TYPICAL CHARACTERISTICS

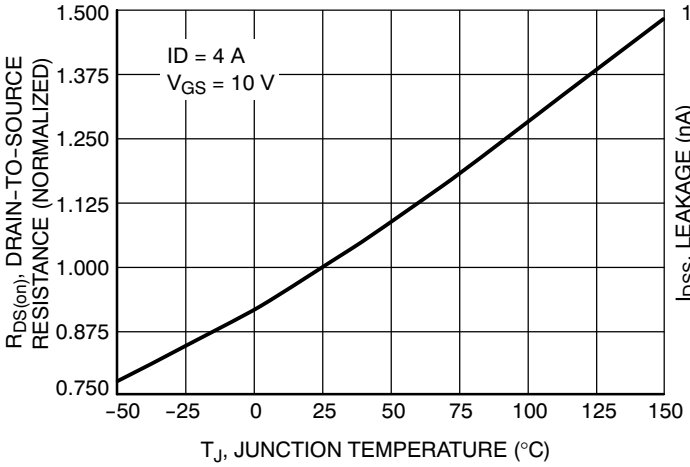


Figure 5. On−Resistance Variation with Temperature

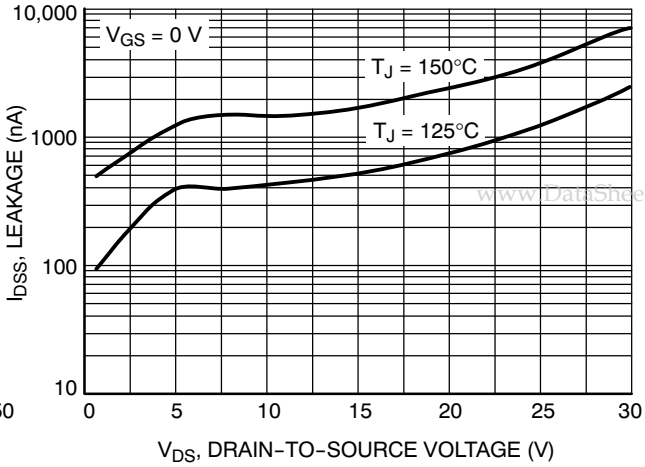


Figure 6. Drain−to−Source Leakage Current vs. Voltage

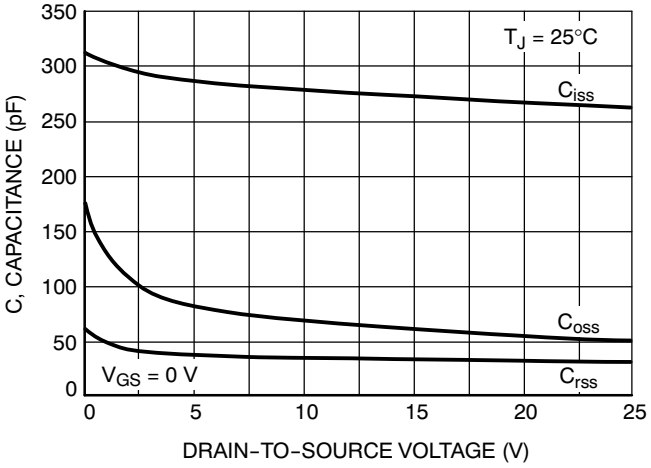


Figure 7. Capacitance Variation

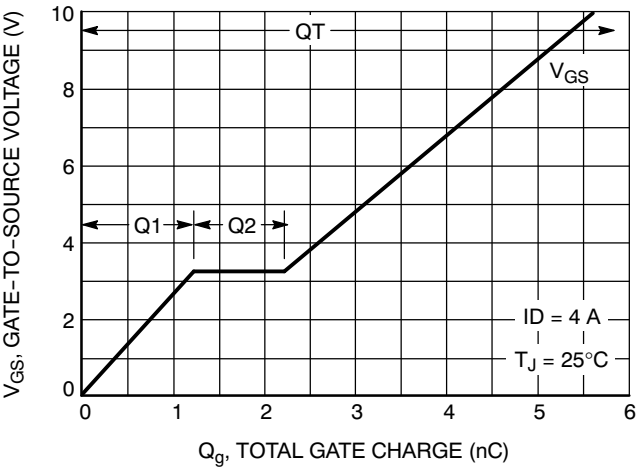


Figure 8. Gate−to−Source and Drain−to−Source Voltage vs. Total Charge

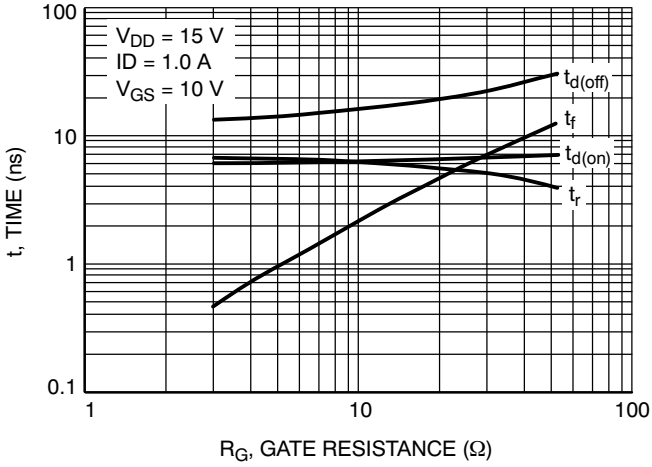


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

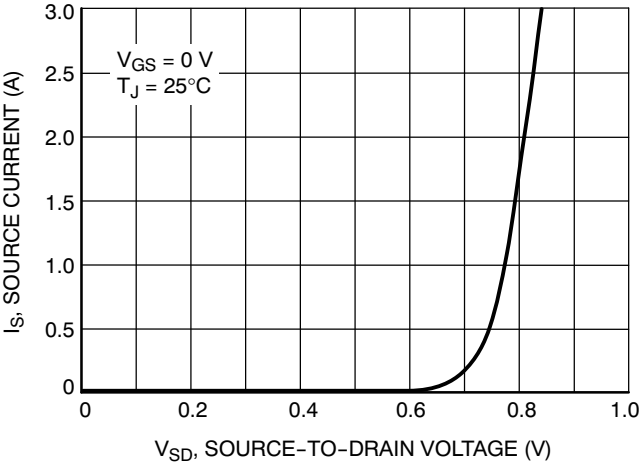


Figure 10. Diode Forward Voltage vs. Current

TYPICAL CHARACTERISTICS

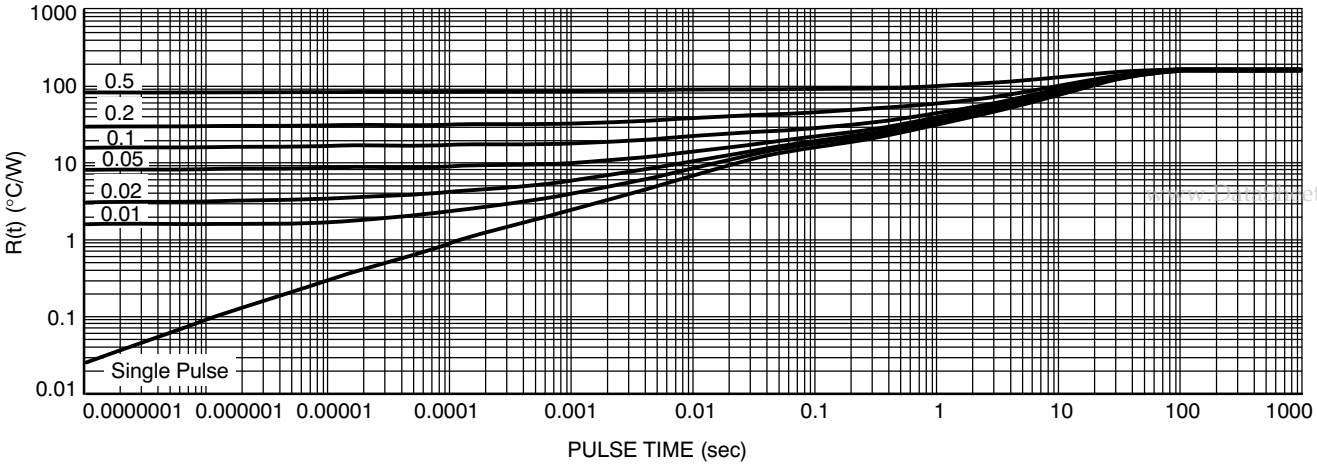


Figure 11. Thermal Response – $R_{\theta JA}$ at Steady State (min pad)

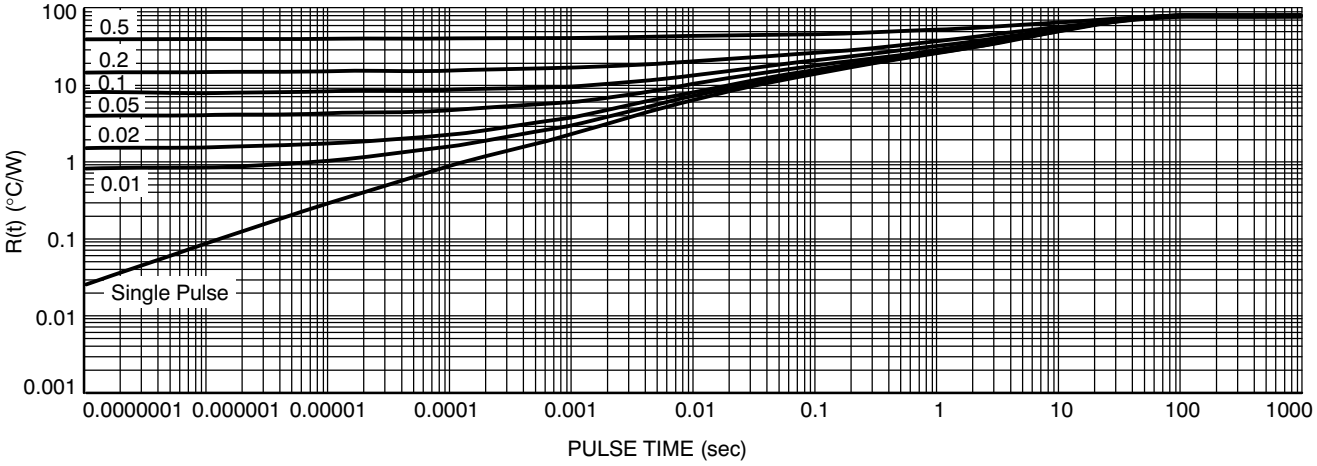


Figure 12. Thermal Response – $R_{\theta JA}$ at Steady State (1 inch sq pad)

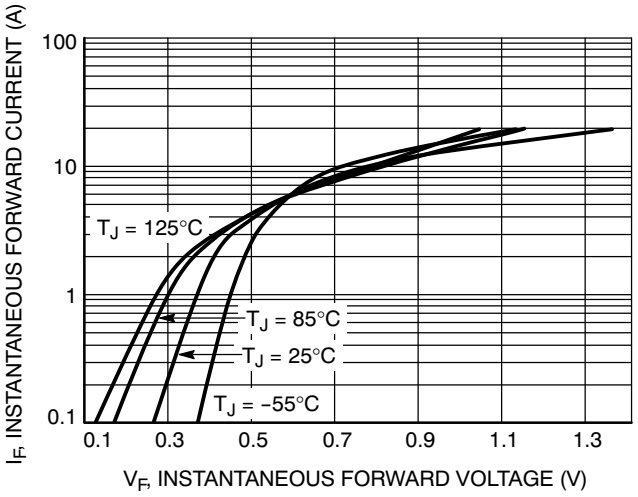


Figure 13. Typical Forward Voltage

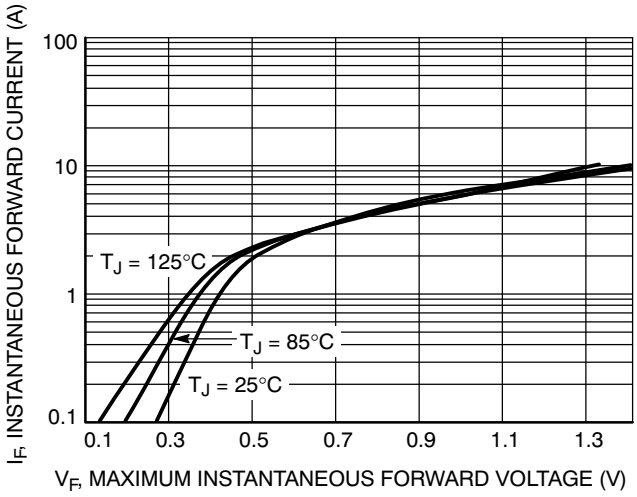


Figure 14. Maximum Forward Voltage

TYPICAL CHARACTERISTICS

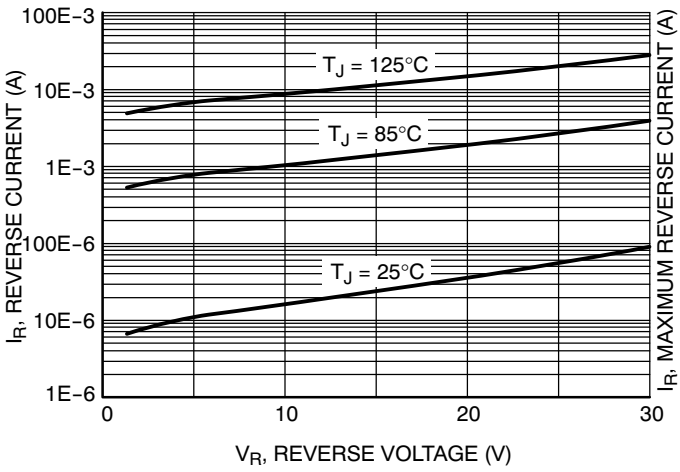


Figure 15. Typical Reverse Current

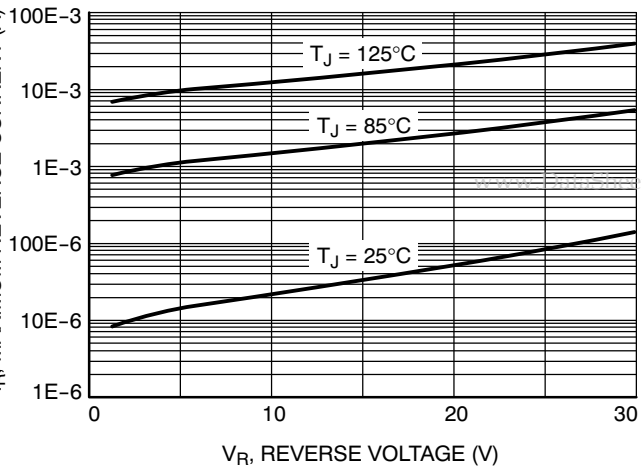


Figure 16. Maximum Reverse Current

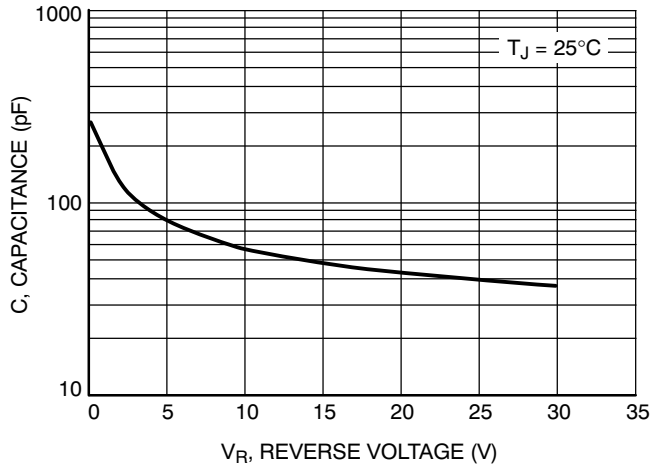
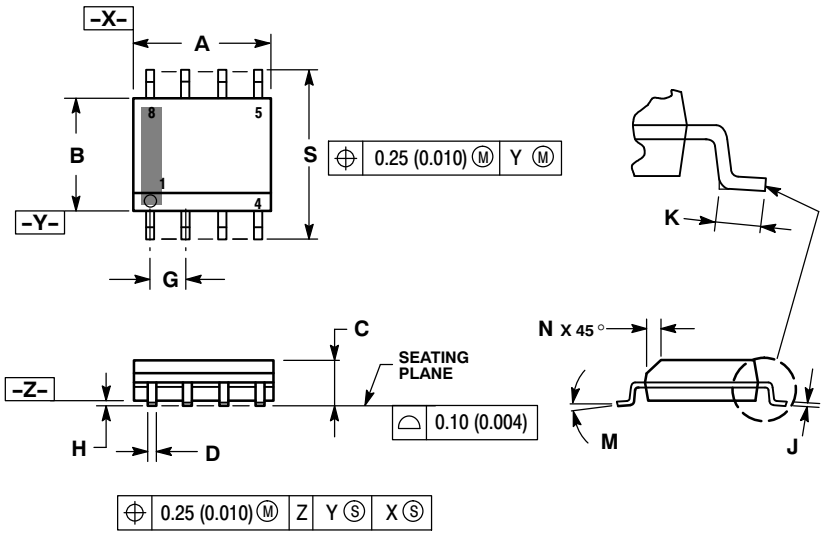


Figure 17. Capacitance

PACKAGE DIMENSIONS

SOIC−8 NB
CASE 751−07
ISSUE AH

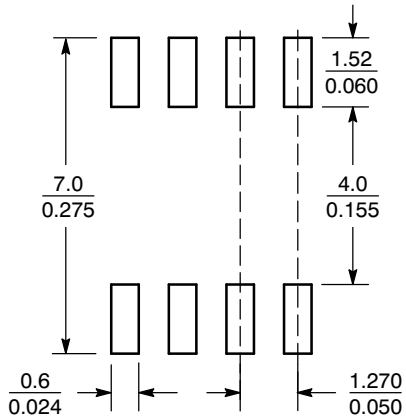


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751−01 THRU 751−06 ARE OBSOLETE. NEW STANDARD IS 751−07.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

STYLE 18:
PIN 1. ANODE
2. ANODE
3. SOURCE
4. GATE
5. DRAIN
6. DRAIN
7. CATHODE
8. CATHODE

SOLDERING FOOTPRINT*



SCALE 6:1 $\left(\frac{mm}{inches}\right)$

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

FETKY is a registered trademark of International Rectifier Corporation.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303−675−2175 or 800−344−3860 Toll Free USA/Canada
Fax: 303−675−2176 or 800−344−3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800−282−9855 Toll Free USA/Canada

Japan: ON Semiconductor, Japan Customer Focus Center
2−9−1 Kamimeguro, Meguro−ku, Tokyo, Japan 153−0051
Phone: 81−3−5773−3850

ON Semiconductor Website: http://onsemi.com

Order Literature: http://www.onsemi.com/litorder

For additional information, please contact your local Sales Representative.